Association Connecting Electronics Industries

IPC

FED

IPC/FED Conference on Embedded Components

4–5 June 2013

Frankfurt, Germany | Hotel InterContinental Frankfurt

Explore the latest developments in embedded component technology at the **IPC/FED Conference on Embedded Components.** Designed to bring the entire supply chain together, this conference will provide you with valuable access to industry experts who are advancing embedded components technology, including OEMs, fabricators, assemblers and designers. Receive the valuable information you need on reliability, test, assembly issues and new manufacturing methods in an efficient two-day program in an intimate setting conducive to networking.

In addition, a tabletop exhibition will showcase leading industry suppliers who will be available to answer your questions on embedded components technology.

If you are a designer, manufacturer, supplier or end-user of embedded components technology, this conference is a must.

See you in Frankfurt!

Sincerely

Stephan Weyhe
Business Manager
FED

Sanjay Huprikar
Vice President,
Member Success
IPC

Who Should Attend

This event is for engineers, designers, marketers, sales professionals and decisions makers with an interest in embedded components technology. It is applicable to every area of the industry, including:

- OEMs
- Assemblers
- Fabricators
- Designers
- Suppliers of materials, equipment, CAD and design services

Pricing

	IPC/FED Member	Industry Rate
Full Two-Day Conference*	€ 620	€ 860
One-Day Conference**	€ 340	€ 470

Pricing does not include German VAT of 19%.
Supplier is VMC. Payments should be made to IPC.

* Includes both days of the conference, two networking lunches, networking reception, exhibition and translation services.
** Includes one day of the conference, networking lunch, exhibits and translation services

Translation Services

(most presentations will be in English)
English–German translation services are included in the cost of registration.

Register Now at
www.ipc.org/embedded-registration

Agenda

Tuesday, 4 June 2013

09:00 Check-in and Exhibits

09:30 Welcome and Introductions

09:45 **Embedded Component Technology in Present and Future**
Jürgen Wolf, Assistant Manager of Research and Development, Würth Elektronik

10:30 **The Progress of Embedded Optical Waveguides in PCBs**
Happy Holden, Director of Electronics Engineering and Innovation, Gentex

11:15 Break/Exhibits

11:45 **Overview: Introduction in Embedded Technologies**
Andreas Ostmann, Group Manager, Embedding & Substrates, Fraunhofer, IZM

12:30 **Achieving New Levels of Functional Density in Mobile Multimedia Devices Using the Z-dimension**
Hemant Shah, Product Marketing Director, Cadence Design Systems, Inc.

13:15 Lunch/Exhibits/Networking

14:45 **Requirements for Embedded Components Pick & Place Technology**
Sjef van Gastel, Manager of Advanced Development, Assembléon
Patrick Huberts, Product Manager, Assembléon

15:30 **Design with and Design for Embedded Components — Electronic Design Process Requirements and Today's Solutions**
Ralf Brüning, Production Manager High Speed Design Solutions, Zuken

16:15 **Design and Assembly Process Implementation for Embedding Passive and Active Components**
Vern Solberg, Consultant, Invensas

17:00 Reception

Wednesday, 5 June 2013

09:00 Exhibits

09:30 **Design Flow for Embedded Actives**
Per Viklund, Director of IC Packaging & RF, Mentor Graphics

10:15 **Embedded Technology and its Introduction in Serial Production**
Mike Morianz, Manager, Technology and Innovation Advanced Packaging, AT&S Leoben, Österreich

11:00 Break/Exhibits

11:30 **Embedding of Passives and Active Components in a Rigid-Flex Printed Circuit Board**
Michael Matthes, Development Engineer, Wittenstein Electronics GmbH
Dirk Müller, Business Manager, Flow Cad

12:15 **The Development of Challenges and Application Reliability for Next Generation Microelectronic and Electronic Products**
Paul Wang, VP of Global Quality and Technology Engineering, MiTac

13:00 Lunch/Exhibits/Networking

14:30 **Embedded Ultra-Thin Chip Packaging (UTCP) Technology**
Jan Vanfletern, Project Manager, IMEC

15:15 **Embedding: An Idea Enters Mass Production**
Christian Rössle, Vice President of Sales & Marketing, Schweitzer Electronik AG

16:00 **Flex Based Embedded Die 3-D-SiP Technology**
Ted Tessier, CTO, FlipChip International

16:45 End

www.ipc.org/embedded-conference

Hotel Information

The IPC/FED Conference on Embedded Components will take place at:

Hotel InterContinental Frankfurt
Wilhelm-Leuschner Strasse 43
Frankfurt 60329, Germany
€ 169 (single), € 189 (double) Rate includes VAT, service charge, and American breakfast buffet. Make your reservations by e-mail to Frankfurt.reservations@ihg.com or call +49 (0) 69 2605 2444 and state you are with **IPC.**

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